

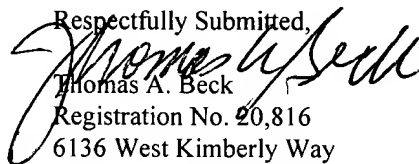
Serial Number : 09/254,769
Filing Date : March 11, 1999
Examiner : V. Nguyen
Group Art Unit : 2829
For :
WAFER SCALE HIGH DENSITY
PROBE ASSEMBLY , APPARATUS FOR
USE THEREOF
AND METHODS OF FABRICATION
THEREOF

Honorable Commissioner of Patents
and Trademarks
Post Office Box 1450
Alexandria, VA 22313-1450

Sir:

ATTORNEY'S CHANGE OF ADDRESS

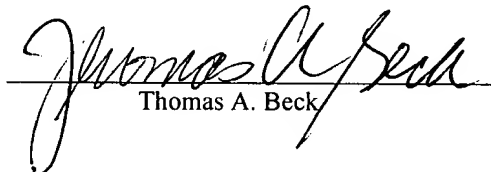
Please send all future communications in this application to the undersigned at 6136 West Kimberly Way, Glendale,
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Respectfully Submitted,

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being transmitted by the United States Postal Service, First Class mail
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July 7, 2007


Thomas A. Beck